

SSC8064GS6

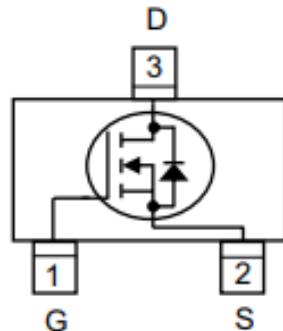
N-Channel Enhancement Mode MOSFET

➤ Features

VDS	VGS	RDS(on) Typ.	ID
60V	±20V	78mR@10V	3A
		84mR@4V5	

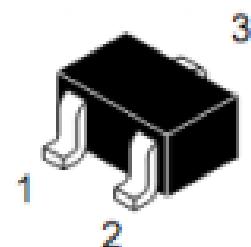
➤ Pin configuration

Top view



➤ Description

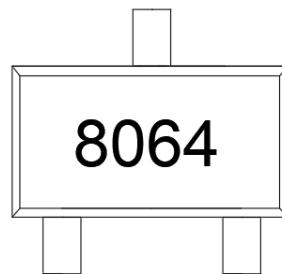
This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device is suitable for use in battery powered system, power switch and portable devices.



SOT23

➤ Applications

- Load Switch
- Portable Devices
- Battery Powered System



Marking

➤ Ordering Information

Device	Package	Shipping
SSC8064GS6	SOT23	3000/Reel

➤ **Absolute Maximum Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	60	V
V_{GSS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current ^a	3	A
I_{DM}	Pulsed Drain Current ^b	12	A
P_D	Power Dissipation ^a	1.0	W
T_J	Operation junction temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^\circ\text{C}$

➤ **Thermal Resistance Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	116.5	$^\circ\text{C}/\text{W}$

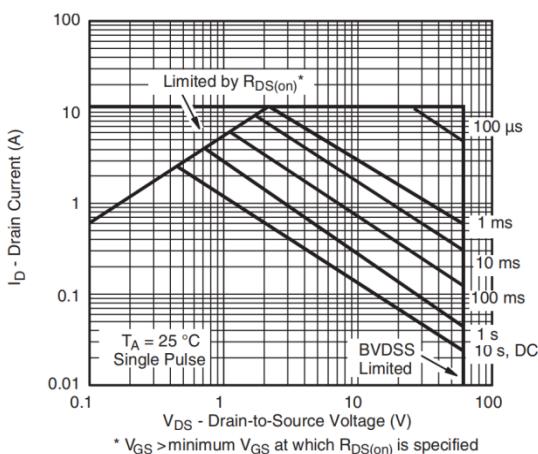
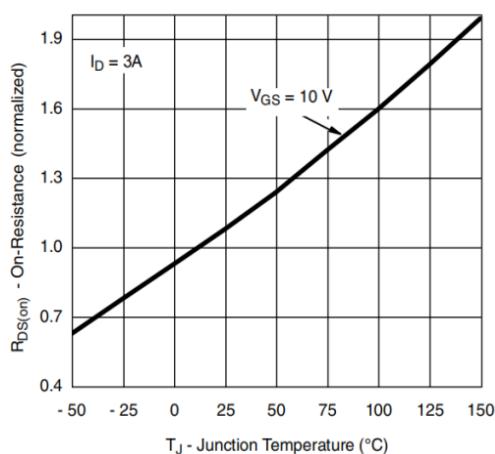
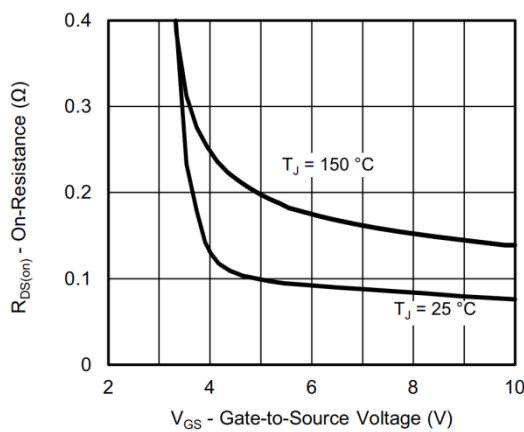
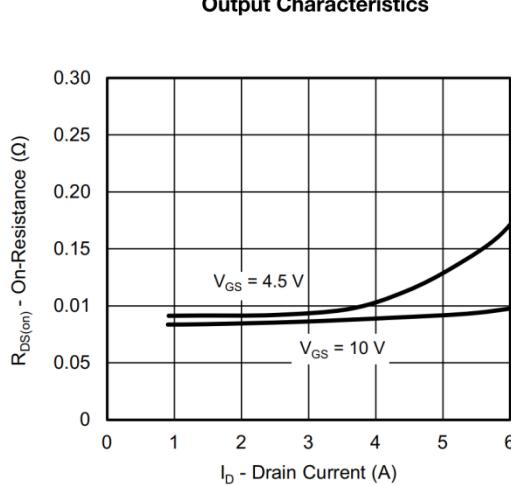
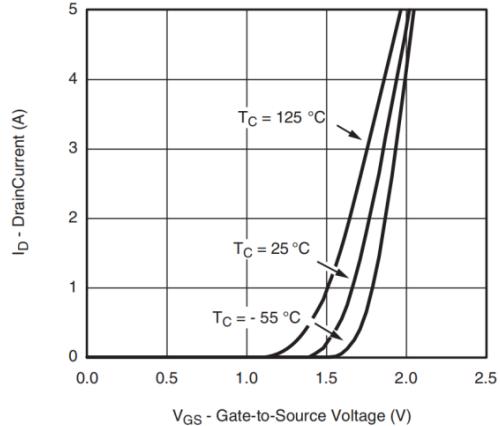
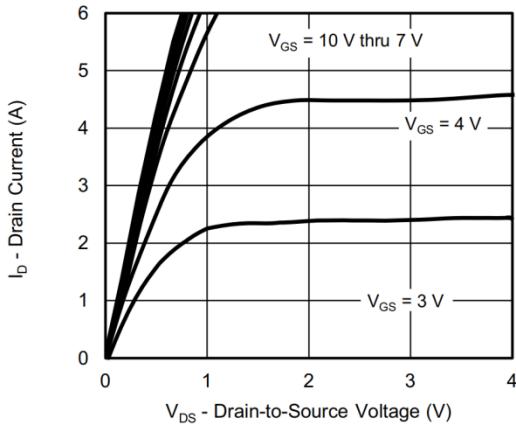
Note:

- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with $T_A=25^\circ\text{C}$.The value in any given application depends on the user specific board design.
- b. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.
- c. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, using steady state junction-to-ambient thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

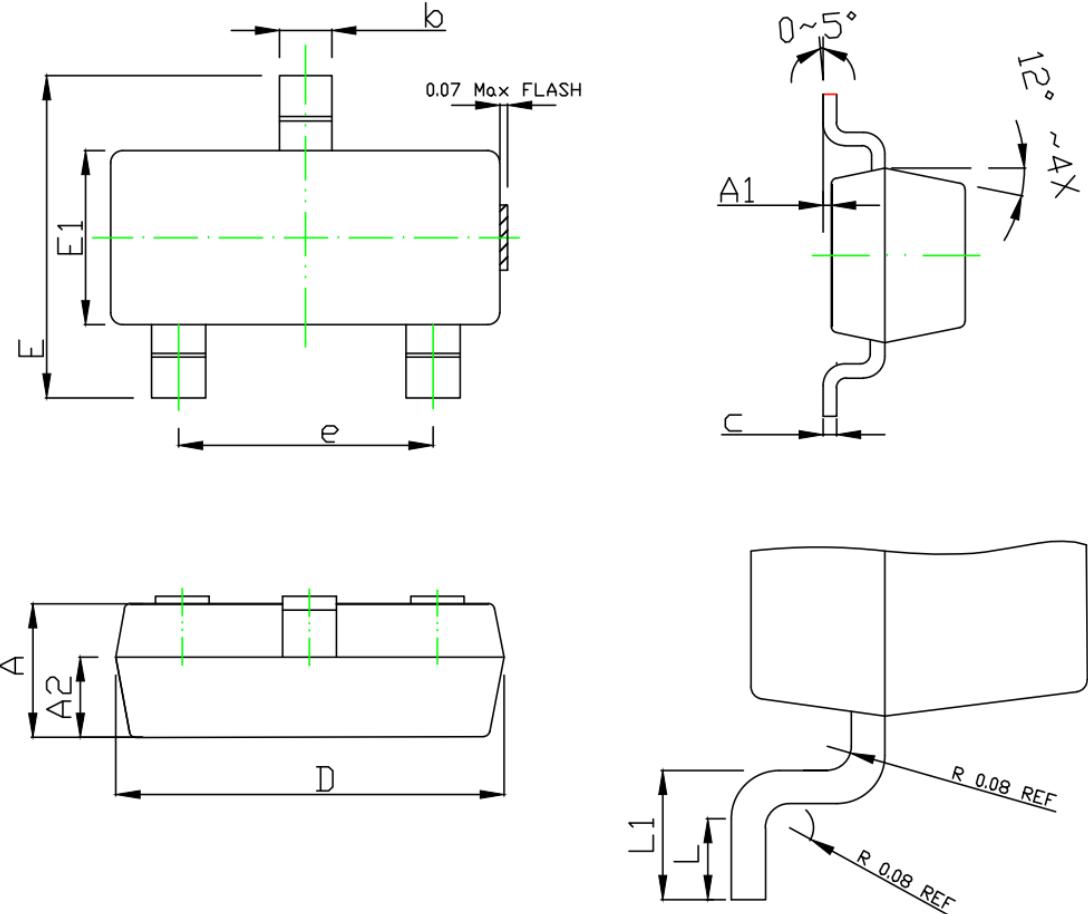
➤ Electronics Characteristics($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $ID=250\mu A$	60			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $ID=250\mu A$	1.0	1.4	2.0	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V$, $ID=3A$		76	100	$m\Omega$
		$V_{GS}=4.5V$, $ID=3A$		84	120	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V$, $V_{GS}=0V$			1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			± 100	nA
G_{FS}	Transconductance	$V_{DS}=5V$, $ID=3A$		5		S
V_{SD}	Forward Voltage	$V_{GS}=0V$, $IS=3A$		0.8	1.4	V
R_g	Gate Resistance	$V_{GS}=0V$, $f=1MHz$		6.0		Ω
C_{iss}	Input Capacitance	$V_{DS}=30V$, $V_{GS}=0V$, $f=1MHz$		402		pF
C_{oss}	Output Capacitance			35		
C_{rss}	Reverse Capacitance			24		
$T_{D(ON)}$	Turn-on delay time	$V_{DS}=30V$, $V_{GEN}=10V$, $RL=10\Omega$ $RG=3\Omega$		3.3		ns
Tr	Rise Time			3.0		
$T_{D(OFF)}$	Turn-off delay time			22		
Tf	Fall Time			7		
Qg	Total Gate charge	$V_{GS}=10V$, $V_{DS}=30V$ $ID=3A$		8.2		nC
Qgs	Gate Source charge			1.0		
Qgd	Gate Drain charge			1.5		
Trr	Diode Recovery Time	$IF=3A$, $di/dt=100A/\mu s$, $VR=30V$		19.5		ns
Qrr	Diode Recovery Charge	$IF=3A$, $di/dt=100A/\mu s$, $VR=30V$		11.5		nC

➤ **Typical Characteristics**($T_A=25^\circ\text{C}$ unless otherwise noted)

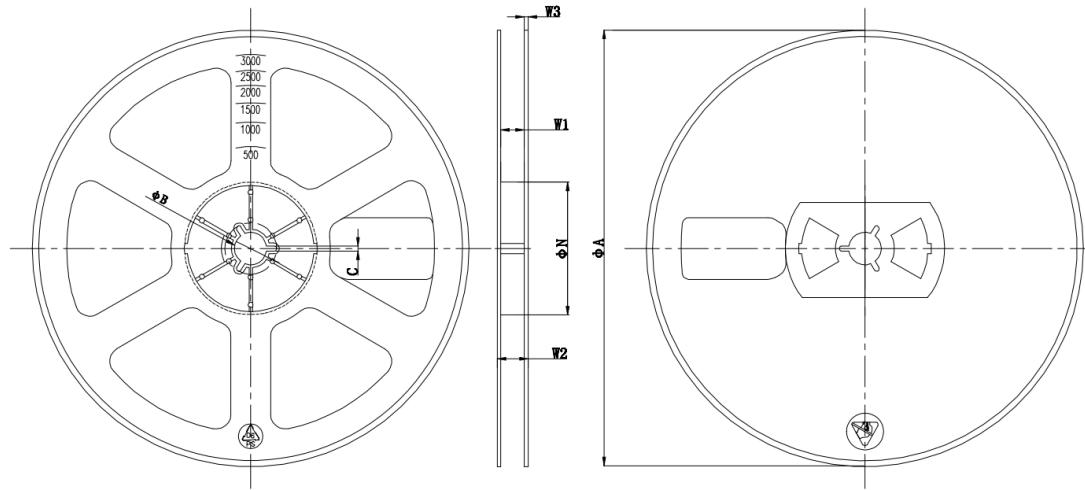


➤ **Package Information**

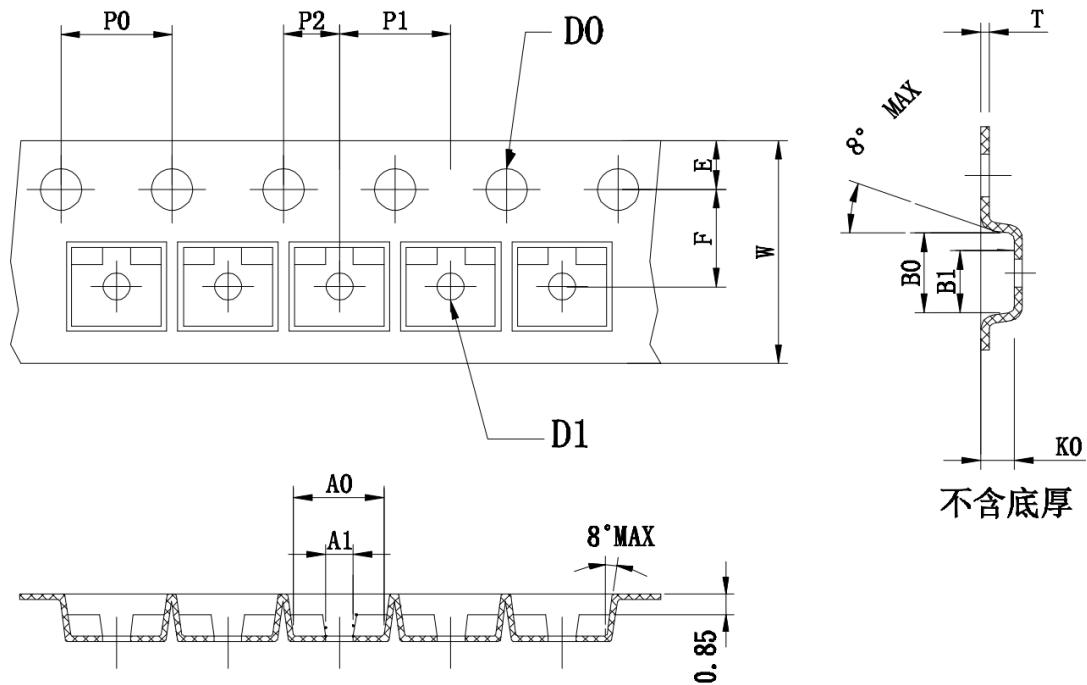


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
A1	0.01	0.05	0.10
b	0.35	0.40	0.45
c	0.11 BSC		
D	2.80	2.90	3.00
E	2.30	2.40	2.50
E1	1.20	1.30	1.40
e	1.90 BSC		
L	0.20	-	-
L1	0.30	0.40	0.50
A2	0.60 REF		

➤ Tape and Reel



ΦA	ΦN	ΦB	C	W_1	W_2	W_3
178 ± 2	54 ± 2	13.2 ± 0.2	2.2 ± 0.3	9.5 ± 1	13_{\max}	1.4 ± 0.4



Symbol	A0	A1	B0	B1	K0	D0	D1	P0
Spec	3.15 ± 0.10	1.15 ± 0.10	2.80 ± 0.10	2.15 ± 0.10	1.30 ± 0.10	1.55 ± 0.10	1.10 ± 0.10	4.00 ± 0.10
Symbol	P1	W	E	P2	T	$10 * P0$	F	
Spec	4.00 ± 0.10	8.00 ± 0.10	1.75 ± 0.10	2.00 ± 0.10	0.21 ± 0.02	40.00 ± 0.10	3.50 ± 0.10	



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